Unapproved Minutes

IEEE P802.3ck 100 Gb/s, 200 Gb/s and 400 Gb/s Electrical Interfaces Task Force

Telephonic interim March 10, 2021
Online Meeting

Prepared by Beth Kochuparambil and Kent Lusted

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IEEE P802.3ck 100 Gb/s Electrical Lane Task Force – March 10, 2021

Prepared by Kent Lusted and Beth Kochuparambil

Proposed Agenda:

- Approval of the Agenda
- Approval of the January Comment Resolution Minutes
- IEEE Participation Requirements reminder
- IEEE Copyright reminder
- IEEE Patent Policy reminder
- Ground Rules and Operations
- Task Force Status
- Technical Presentations
 - "Cp Value Ratification", Karl Bois
 - "Measured vs. Simulated Correlation of Package Model", Mau-Lin Wu
 - "Package to Board Linkage capacitance, Cp: Extraction/Simulation Follow up", Liav Ben-Artsi

Presentations posted at: https://www.ieee802.org/3/ck/public/21 03/index.html

Meeting began at ~7:00 a.m. Pacific by Beth Kochuparambil, IEEE 802.3ck Task Force Chair. (Note: all times are Pacific time zone unless otherwise indicated)

Beth welcomed attendees.

Meeting began with the agenda presentation https://www.ieee802.org/3/ck/public/21_03/agenda_3ck_01a_0321.pdf

The chair reminded participants to indicate full names and employer/affiliation correctly for the meeting minutes. Reminded participants to mute lines when not speaking and reviewed the steps to unmute.

Chair reviewed the proposed agenda and asked if there were modifications to the agenda. Asked if there was objection to agenda as shown. No one responded. Chair considered the agenda approved.

Chair noted that the minutes for the January comment resolution series had been posted to the website (see:

https://www.ieee802.org/3/ck/public/21_01/minutes_3ck_0121_final_unapproved.pdf) . Chair asked if there was opposition to approving the posted minutes. No one responded. Chair considered the minutes approved.

Chair reviewed the slide with the Participation requirements.

Chair asked if anyone participating had not read the copyright slide set – no one responded. Chair showed the IEEE-SA copyright slides.

Chair asked if anyone participating had not read the patent slide set – no one responded. Chair showed the patent policy slides and did the call for Potentially Essential Patents – no one responded.

Chair reviewed the ground rules.

Chair called for members of the press. No one responded.

Chair reminded participants to sign into the IEEE Meeting Attendance Tool to record attendance for the IEEE 802.3 Working Group. Task Force attendance would be taken from the webex logs.

Task Force Status - Beth Kochuparambil

See: https://www.ieee802.org/3/ck/public/21 03/agenda 3ck 01a 0321.pdf

- Reviewed comment statistics from D1.4.
- Draft 1.5 was posted on 3 March 2021 in the Task Force private area
- Reviewed the plan to request the Working Group ballot on 18 March in the Working Group closing plenary.

Vice Chair reminded participants to declare their affiliation either in their webex ID or via the webex chat window.

Motion #1:

Move to:

- Generate Draft 2.0 from Draft 1.5
- Request that IEEE 802.3 WG progress the draft to Working Group ballot.

M: Rich MellitzS: Ali GhiasiTechnical (>=75%)

There was an objection during the vote. Chair indicated that she would proceed with a roll call vote. The objection was clarified to be an abstention. There was discussion on how to proceed. Chair declared that she would retake the vote and ask if there were abstentions.

Chair asked if there was anyone opposed to the motion. No one responded. Chair asked if anyone wanted to be recorded as abstain. Piers Dawe indicated that he wanted to be recorded as abstain.

Chair announced motion passed by unanimous consent. Piers Dawe abstained from the vote.

Presentation #1:

"Cp Value Ratification", Karl Bois

See: https://www.ieee802.org/3/ck/public/21 01/bois 3ck 01 0121.pdf

- Discussed various aspects of the 3D simulation on slide 7.
- Discussed the parameters used in analysis.

Presentation #2:

"Measured vs. Simulated Correlation of Package Model", Mau-Lin Wu See: https://www.ieee802.org/3/ck/public/21_01/wu_3ck_02_0121.pdf

- Discussed the process to determine the rise time of the TDR
- On slide 7, the Cd_60 and Cd_87 use the same package model; only the Cd value changes.
- On slide 5, it was noted that the measurement was from bump pad to TPOv.

Presentation #3:

"Package to Board Linkage capacitance, Cp: Extraction/Simulation Follow up", Liav Ben-Artsi See: https://www.ieee802.org/3/ck/public/21_03/benartsi_3ck_01b_0321.pdf

- Discussed the plots on slide 5.
- Reviewed the topology details on slide 12.

Chair encouraged offline consensus building and discussion on the Cp topic as it would be a key topic in Working Group ballot.

Chairn reminded participants of the-mid session meeting on 11 March. The Task Force will request a Working Group ballot at the closing plenary on 18 March. Watch the email reflector for more details.

Meeting ended at ~9:00 a.m.

Attendees

Name	Affiliation	Employed by
Adam Healey	Broadcom	Broadcom
Adee Ran	Cisco	Cisco
Alan Kinningham	I-PEX	I-PEX
Alex Haser	Molex	Molex
Ali Ghiasi	Ghiasi Quantum/Inphi	Ghiasi Quantum/Inphi
Arthur Marris	Cadence	Cadence
Ayal Shoval	Synopsys	Synopsys
Bernd Horrmeyer	Phoenix Contact	Phoenix Contact
Beth Kochuparambil	Cisco	Cisco
Bo Zhang	Inphi	Inphi
Brandon Gore	Samtec	Samtec
Bruce Champion	TE Connectivity	TE Connectivity
Burrell Best	Samtec	Samtec
Champion (Chien Ping) Kao	Cornelis Networks	Cornelis Networks
Chan Chih (David) Chen	Applied Optoelectronics	Applied Optoelectronics
Clint Walker	Alphawave IP	Alphawave IP
Dave Estes	Spirent	Spirent
David Malicoat	Senko	Independent
David Piehler	Dell EMC	Dell EMC
David Rennie	Synopsys	Synopsys
Ed Frlan	Semtech	Semtech

Ed sayre	Samtech	NESA
Ed Ulrichs	Intel	Intel
Edward Nakamoto	Spirent	Spirent
Fernando Barbero	KDPOF	KDPOF
Frank Chang	Source Photonics	Source Photonics
Geoff Zhang	Xilinx	Xilinx
Guangcan Mi	Huawei	Huawei
Haifei Wang	Huawei	Huawei
Hansel Dsilva	Achronix	Achronix
Hao Ren	Huawei	Huawei
Haysam Kadry	Ford Motor Company	Ford Motor Company
Hessam Mohajeri	Cadence	Cadence
Howard Heck	Intel	Intel
Inho Kim	Max Linear	Max Linear
Jacky Chang	HPE	НРЕ
James Weaver	Arista	Arista
James Young	Commscope	Commscope
Jane Lim	Cisco	Cisco
Jeff Slavick	Broadcom	Broadcom
Jeffery Maki	Juniper	Juniper
Jennifer Santulli	IEEE SA	IEEE SA
Jinhua Chen	Luxshare ICT	Luxshare ICT
Joel Goergen	Cisco Systems, Inc.	Cisco Systems, Inc.
John Calvin	Keysight	Keysight

John Deandrea	II-VI/Finisar	II-VI/Finisar
John Ewen	Marvell	Marvell
John Kamino	OFS Optics	OFS Optics
Jose Castro	Panduit	Panduit
Joshua Kim	Hirose	Hirose
Karen Liu	Lightwave Logic	Lightwave Logic
Karl Bois	TE Connectivity	TE Connectivity
KengHua Chuang	НРЕ	НРЕ
Kent Lusted	Intel	Intel
Kishore Kota	Inphi	Inphi
Kukita Hiroaki	Yamaichi	Yamaichi
Kumaran Krishnasamy	Broadcom	Broadcom
Liav Ben-Artsi	Marvell	Marvell
Mabud Choudhury	OFS	OFS
Mario Milicevic	Maxlinear	Maxlinear
Mark Gustlin	Cisco	Cisco
Mark Kimber	Semtech	Semtech
Mark Nowell	Cisco	Cisco
Matt Brown	Huawei	Huawei
Mau-Lin Wu	Mediatek	Mediatek
Mike Dudek	Marvell	Marvell
Mike Klempa	Amphenol	Amphenol
Mike Li	Intel	Intel
Mike Sluyski	Acacia	Acacia

Nathan Tracy	TE Connectivity	TE Connectivity
Patrick Casher	Foxconn Interconnect	Foxconn Interconnect
Paul Brooks	Viavi	Viavi
Phil Sun	Credo	Credo
Piers Dawe	NVIDIA	NVIDIA
Pirooz Tooyserkani	Cisco	Cisco
Pranav Devalla	Arista	Arista
Rajmohan Hegde	Broadcom	Broadcom
Rich Mellitz	Samtec	Samtec
Rick Pimpinella	Panduit	Panduit
Rick Rabinovich	Keysight	Keysight
Rita Horner	Synopsys	Synopsys
Roberto Rodes	Finisar	Finisar
Sam Kocsis	Amphenol	Amphenol
Scott Sommers	Molex	Molex
Scott Walley	Max Linear	Max Linear
Shimon Muller	Axalume	Axalume
Sina Shahi	Huawei	Huawei
SJ Yu	Foxconn Interconnect	Foxconn Interconnect
Sridhar Ramesh	Independent	Independent
Stephen Didde	Keysight	Keysight
Takeshi Nishimura	Yamaichi, USA	Yamaichi, USA
Terry Little	Foxconn Interconnect	Foxconn Interconnect
Tom Issenhuth	Huawei	Issenhuth Consulting

Tom Palkert	Macom/Samtec	Macom/Samtec
Toshiaki Sakai	Socionext	Socionext
Upen Kareti	Cisco	Cisco
Viet Tran	Keysight	Keysight
Yang Zhiwei	ZTE	ZTE
Yasuo Hidaka	Credo	Credo
Yi Sun	OFS Optics	OFS Optics
Yong Kim	Axonne	Axonne
Yu (Helen) Xu	Huawei	Huawei
Zhiwei Yang	ZTE	ZTE